PCN Number: 20200507000.1 PCN Date: May 08, 2020							
Title: Qualification of TI Malaysia as an additional Assembly site for Select Devices							
Customer Contact:	Customer Contact: PCN Manager Dept: Quality Services						
Proposed 1 st Ship D	ate: Aug (08, 2020		Estimate		mple pility:	Date provided at sample request
Change Type:				AV	anaı	mity:	Sample request
Assembly Site		Desig	ın		ПП	Wafe	r Bump Site
Assembly Process			Sheet		ΙĦ		r Bump Material
Assembly Materia			number	change			r Bump Process
Mechanical Specif	ication	Test		_		Wafe	r Fab Site
Packing/Shipping,	/Labeling	Test	Process				r Fab Materials
						Wafe	r Fab Process
D : 1: COL		PC	N Deta	ails			
Description of Chan	ge:						
Texas Instruments is pleased to announce the qualification of TI Malaysia as an additional assembly site for the list of devices below. There are no construction differences between the current and new site.							
Reason for Change:							
Continuity of Supply							
Anticipated impact	on Form, Fit	t, Functio	n, Qua	ity or Relia	bilit	y (pos	sitive / negative):
None							
Anticipated impact							
No Impact to the Material Declarat	tion fr	om produ roduction eports can	ction da release. be obta	ta and will be Upon produ ined at the s	e ava action site li	ailable n relea ink bel	eports are driven following the se the revised ow ntentsearch.tsp
Changes to product identification resulting from this PCN:							
Assembly Site							
TI Taiwan	TAI			TWN	(Chung Ho
TI Malaysia		MLA		MYS			Kuala Lumpur
Sample product shipping label (not actual product label) TEXAS INSTRUMENTS MADE IN: Malaysia 2DC: 20: MSL '2 /260C/1 YEAR SEAL DT MSL 1 /235C/UNLIM 03/29/04 OPT: ITEM: 39 LBL: 5A (L) T0: 1750 Product Affected: (1P) \$N74L\$07N\$R (Q) 2000 (D) 0336 (31T) LOT: 3959047MLA (4W) TKY(1T) 7523483S12 (P) (2P) REV: (V) 0033317 (20L) C50: SHE (21L) CC0: USA (22L) AS0: MLA (23L) ACO: MYS							

ISO7730DW	ISO7731DWR	ISO7740FDW	ISO7741FBDWR
ISO7730DWR	ISO7731FBDW	ISO7740FDWR	ISO7741FDW
ISO7730FDW	ISO7731FBDWR	ISO7741BDW	ISO7741FDWR
ISO7730FDWR	ISO7731FDW	ISO7741BDWR	ISO7742DW
ISO7731BDW	ISO7731FDWR	ISO7741DW	ISO7742DWR
ISO7731BDWR	ISO7740DW	ISO7741DWR	ISO7742FDW
ISO7731DW	ISO7740DWR	ISO7741FBDW	ISO7742FDWR
•	<u> </u>	<u> </u>	<u> </u>



Qualification Report

Approve Date 30-Apr-2020

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Туре	Test Name / Condition	Duration	Qual Device: ISO7741FDW	QBS Package Reference: <u>ISO1050DUB</u>
AC	Autoclave 121C	96 Hours	3/231/0	-
HAST	Biased HAST, 130C/85%RH	96 Hours	-	3/231/0
HTOL	Life Test, 125C	1000 Hours	-	3/150/0
HTSL	High Temp Storage Bake 175C	500 Hours	3/231/0	-
TC	Temperature Cycle, -65/150C	500 Cycles	3/231/0	-
WBP	Bond Pull	Wires	3/228/0	3/228/0
WBS	Ball Bond Shear	Wires	3/228/0	3/228/0

- QBS: Qual By Similarity
- Qual Device ISO7741FDW is qualified at LEVEL2-260C
- Device ISO7741FDW contains multiple dies.
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7 eV: 150 C/1 k Hours, and 170 C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles Quality and Environmental data is available at TI's external Web site: http://www.ti.com/Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

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